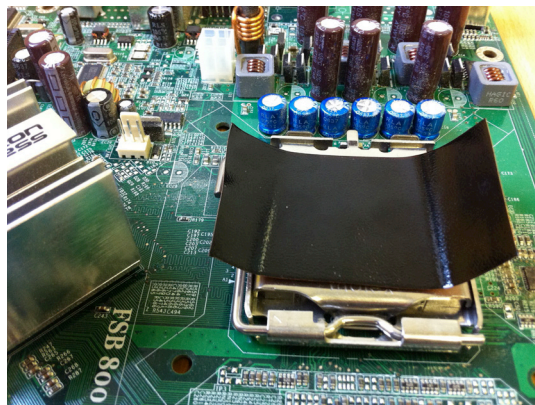


PH3n

High Performance Heat Spreader



Features

Gives a typical junction temperature reduction of 20°C
Gives design flexibility
Die cut for custom shapes

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Properties

-  REACH Compliant
-  RoHS Compliant

Property	PH3n			Test Method	Unit
Colour	Black	Black	Black	Visual	-
Thickness	0.062	0.07	0.1	-	mm
Metal layer	CU foil	CU foil	CU foil	-	-
PET layer thickness	0.025	0.025	0.025	ADTM D374	mm
Coating layer thickness	0.025	0.025	0.025	-	mm
Metal layer thickness	0.012	0.02	0.02	-	mm
Filler	Nano tube	Nano tube	Nano tube	-	-
Application temperature	-30 to 120	-30 to 120	-30 to 120	-	°C
Short time temp. @ 30sec	200	200	200	-	°C
Low molecular weight Siloxane content	0	0	0	-	ppm
Heat emissivity coefficient	0.96	0.96	0.96	ADTM D149	1
Dielectric strength (AV)	>2	>2	>2	ADTM D149	kV
Metal layer thermal conductivity	400	400	400	ADTM D5470	W/mk
Coated layer thermal conductivity	1.2	1.2	1.2	ADTM D5470	W/mk

Available with an adhesive backing



PH3n $\frac{x}{15} \frac{y}{20} \frac{z}{0.062/0.07}$

1. Part Number
2. Size X-Y-Z